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PATENT  
Attorney Docket No.: 16869P-010700US  
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Assistant Commissioner for Patents  
Washington, D.C. 20231

On January 3, 2003

TOWNSEND and TOWNSEND and CREW LLP

By: James Quinn Can

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:

Kouichi Takahashi, et al.

Application No.: 09/590,897

Filed: June 9, 2000

For: SEALING STRUCTURE FOR  
MULTI-CHIP MODULE

Examiner: James M. Mitchell

Art Unit: 2827

AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed August 28, 2002, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 4, line 28 with the following rewritten paragraph:

--A gap allowing for the precision of assembly and the difference in thermal expansion is provided between the side face of the inside middle stage of the upper frame 10 and that of the circumference of the air-cooled heat sink 7, and a fine gap is provided between the upper face of the frame 5 and the under face of the circumference of the air-cooled heat sink 7 to avoid their contact while maintaining the hermetic sealing provided by the rubber O ring 15. Thus deformation of the module in its vertical